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APPLICATION NO.	FILING DATE	FIRST NAMED INVENTOR	ATTORNEY DOCKET NO.	CONFIRMATION NO.
10/814,482	03/31/2004	Toshiharu Furukawa	ROC920030399USI	6082
30206 7590 12/22/2006 IBM CORPORATION			EXAMINER	
ROCHESTER	IP LAW DEPT. 917	GOODWIN, DAVID J		
	AY 52 NORTH , MN 55901-7829		ART UNIT	PAPER NUMBER
TO CITED I EIT,	1111 33301 7023		2818	
SHORTENED STATUTOR	RY PERIOD OF RESPONSE	MAIL DATE	DELIVERY MODE	
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Please find below and/or attached an Office communication concerning this application or proceeding.

If NO period for reply is specified above, the maximum statutory period will apply and will expire 6 MONTHS from the mailing date of this communication.

Office Action Summary		Application No.	Applicant(s)		
		10/814,482	FURUĶAWA ET AL.		
		Examiner	Art Unit		
		David Goodwin	2818		
Period fo	The MAILING DATE of this communication ap or Reply	opears on the cover sheet with th	ne correspondence address		
WHIC - Exter after - If NO - Failu Any r	ORTENED STATUTORY PERIOD FOR REPLEHEVER IS LONGER, FROM THE MAILING It is ions of time may be available under the provisions of 37 CFR 1. SIX (6) MONTHS from the mailing date of this communication. It is period for reply is specified above, the maximum statutory period re to reply within the set or extended period for reply will, by stature eply received by the Office later than three months after the mailing patent term adjustment. See 37 CFR 1.704(b).	DATE OF THIS COMMUNICAT .136(a). In no event, however, may a reply but divided will apply and will expire SIX (6) MONTHS atte, cause the application to become ABAND	ION. le timely filed from the mailing date of this communication. DNED (35 U.S.C. § 133).		
Status					
2a) <u></u>	Responsive to communication(s) filed on <u>01 l</u> This action is FINAL . 2b) This ince this application is in condition for allowed closed in accordance with the practice under	is action is non-final. ance except for formal matters,	γ.		
Dispositi	on of Claims				
5)□ 6)⊠ 7)□	Claim(s) 1-15 is/are pending in the application 4a) Of the above claim(s) is/are withdra Claim(s) is/are allowed. Claim(s) 1-15 is/are rejected. Claim(s) is/are objected to. Claim(s) are subject to restriction and/	awn from consideration.	:		
Applicati	on Papers				
10)	The specification is objected to by the Examin The drawing(s) filed on is/are: a) ac Applicant may not request that any objection to the Replacement drawing sheet(s) including the corre The oath or declaration is objected to by the E	ccepted or b) objected to by the drawing(s) be held in abeyance.	See 37 CFR 1.85(a). objected to See 37 CFR 1.121(d).		
Priority L	ınder 35 U.S.C. § 119		•		
12) Acknowledgment is made of a claim for foreign priority under 35 U.S.C. § 119(a)-(d) or (f). a) All b) Some * c) None of: 1. Certified copies of the priority documents have been received. 2. Certified copies of the priority documents have been received in Application No. 3. Copies of the certified copies of the priority documents have been received in this National Stage application from the International Bureau (PCT Rule 17.2(a)). * See the attached detailed Office action for a list of the certified copies not received.					
2) Notice 3) Information	t(s) se of References Cited (PTO-892) se of Draftsperson's Patent Drawing Review (PTO-948) mation Disclosure Statement(s) (PTO/SB/08) ser No(s)/Mail Date	4) Interview Summ Paper No(s)/Ma 5) Notice of Inform 6) Other:	il Date		

DETAILED ACTION

Claim Rejections - 35 USC § 112

1. The following is a quotation of the second paragraph of 35 U.S.C. 112:

The specification shall conclude with one or more claims particularly pointing out and distinctly claiming the subject matter which the applicant regards as his invention.

- 2. Claim 15 is rejected under 35 U.S.C. 112, second paragraph, as being indefinite for failing to particularly point out and distinctly claim the subject matter which applicant regards as the invention.
- 3. Claim 15 depends on canceled claim 16. The limits of the claim are therefore indeterminate.
- 4. Claim 15 recites the limitation "said first and second anchors" "said island and "said strained region. There is insufficient antecedent basis for this limitation in the claim.

Claim Rejections - 35 USC § 102

The following is a quotation of the appropriate paragraphs of 35.
U.S.C. 102 that form the basis for the rejections under this section made in this
Office action:

A person shall be entitled to a patent unless -

(e) the invention was described in (1) an application for patent, published under section 122(b), by another filed in the United States before the invention by the applicant for patent or (2) a patent granted on an application for patent by another filed in the United States before the invention by the applicant for patent, except that an international application filed under the treaty defined in section 351(a) shall have the effects for purposes of this subsection of an application filed in the United States only if the international application designated the United States and was published under Article 21(2) of such treaty in the English language.

2.

- 3. Claims 1-11 and 13-15 are rejected under 35 U.S.C. 102(e) as being anticipated by Wasshuber (US2003/0111699).
- 4. Wasshuber teaches a semiconductor device. Said device comprises an island (524) of semiconductor material having a plurality of sidewalls and a strained region (paragraph 0031-0032) (fig 22). A handle wafer (514) and an insulating layer (512) disposed between said island (524) and said handle wafer (514). Said insulating layer (512) containing a thick region underlying the strained semiconductor island (524) and said insulating layer (512) electrically isolating said island (524) of said semiconductor material from said handle wafer (514). The underlying thickness of insulator exerts a tensile stress on the strained region (524) (paragraph 0042-0043).
- 5. Regarding claim 2.
- 6. Said insulating layer (512) comprises a buried oxide layer and said island is silicon (paragraph 0020-0021).
- 7. Regarding claim 3.
- 8. Wasshuber teaches a source (522a) and drain (522b) defined in the island (524), and a channel defined in the island between said source and said drain (fig 22) (paragraph 0034-0036). Said channel is disposed at least partially in said strained region of said island (fig 22) (paragraph 0042-0043).
- Regarding claim 4.
- 10. Wasshuber teaches that the gate electrode (540) is isolated from said portion of the island (524) defining said channel (fig 22) (paragraph 0042-0043).

- 11. Regarding claim 5.
- 12. Wasshuber teaches that the insulating material (12b) divides the gate electrode (32) (fig 1) (paragraph 0020-0022).
- 13. Regarding claim 6.
- 14. Wasshuber teaches that the gate electrode overlies the channel (fig 22).
- 15. Regarding claim 7.
- 16. Wasshuber teaches that that the structure comprises a semiconductor device (fig 22) (paragraph 000042-0043).
- 17. Regarding claim 8.
- 18. Wasshuber teaches that the island (524) comprises silicon and the thickness of underlying insulator (512) comprises silicon dioxide (paragraph 0020-0021).
- 19. Regarding claim 9.
- 20. Wasshuber teaches that the thickness of underlying insulator comprises silicon dioxide (paragraph 0020-0021).
- 21. Regarding claim 10.
- 22. Wasshuber teaches that the wafer (514) comprises silicon and the thickness of underlying insulator (512) comprises silicon dioxide (paragraph 0020-0021).
- 23. Regarding claim 11.
- 24. Strained silicon enhances carrier mobility (0003).
- 25. Regarding claim 13.

- 26. The thickened region of said insulating layer (512) has a thickness greater than the surrounding insulating layer flanking said region (fig 22).
- 27. Regarding claim 14.
- 28. First and second anchors flanking the strained region prevent relaxation of the strain region (fig 22).
- 29. Regarding claim 15.
- 30. First and second anchors flanking and adjacent to the strained region prevent relaxation of the strain region (fig 22).

31.

- 32. Claims 1-4, 6-12, 14 and 15 are rejected under 35 U.S.C. 102(e) as being anticipated by Yeo (US 2004/0150042).
- 33. Regarding claim 1
- 34. Yeo teaches a semiconductor device. Said device comprises an island (84) of semiconductor material having a plurality of sidewalls and a strained region (paragraph 0031-0032) (fig 35). A handle wafer (52) and an insulating layer (54) disposed between said island (84) and said handle wafer (52). Said insulating layer (54) containing a thick region underlying the strained semiconductor island (84) and said insulating layer electrically isolating said island (84) of said semiconductor material from said handle wafer (52). The underlying thickness of insulator exerts a tensile stress on the strained region (84) (paragraph 0031).
- 35. Regarding claim 2.

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36. Said insulating layer (54) comprises a buried oxide layer and said island is silicon (paragraph 0031).

- 37. Regarding claim 3.
- 38. Yeo teaches a source defined in the island, a drain defined in the island, and a channel defined in the island between said source and said drain (fig 5) (paragraph 0034-0036). Said channel is disposed at least partially in said strained region of said island (fig 5).
- 39. Regarding claim 4.
- 40. Yeo teaches that the gate electrode is isolated from said portion of the island (84) defining said channel (fig 5) (paragraph 0036).
- 41. Regarding claim 6.
- 42. Yeo teaches that the gate electrode overlies the channel (fig 5).
- 43. Regarding claim 7.
- 44. Yeo teaches that that the structure comprises a semiconductor device (fig 5) (paragraph 0036).
- 45. Regarding claim 8.
- 46. Yeo teaches that the island comprises silicon and the thickness of underlying insulator comprises silicon dioxide (fig 0031).
- 47. Regarding claim 9.
- 48. Yeo teaches that the thickness of underlying insulator comprises silicon dioxide (fig 0031).
- 49. Regarding claim 10.

- 50. Yeo teaches that the wafer comprises silicon and the thickness of underlying insulator comprises silicon dioxide (fig 0031).
- 51. Regarding claim 11.
- 52. Strained silicon enhances carrier mobility (0002).
- 53. Regarding claim 12.
- 54. The thickness of oxide material is more than 5 to 10 nanometers.
- 55. Regarding claim 14.
- 56. First and second anchors flanking the strained region prevent relaxation of the strain region (fig 5).
- 57. Regarding claim 15.
- 58. First and second anchors flanking and adjacent to the strained region prevent relaxation of the strain region (fig 5).

Conclusion

Any inquiry concerning this communication or earlier communications from the examiner should be directed to David Goodwin whose telephone number is (571)272-8451. The examiner can normally be reached on Monday through Friday, 9:00am through 5:00pm.

If attempts to reach the examiner by telephone are unsuccessful, the examiner's supervisor, Matthew Smith can be reached on (571)272-1907. The fax phone number for the organization where this application or proceeding is assigned is 571-273-8300.

Information regarding the status of an application may be obtained from the Patent Application Information Retrieval (PAIR) system. Status information for published applications may be obtained from either Private PAIR or Public PAIR. Status information for unpublished applications is available through Private PAIR only. For more information about the PAIR system, see http://pair-direct.uspto.gov. Should you have questions on access to the Private PAIR system, contact the Electronic Business Center (EBC) at 866-217-9197 (toll-free). If you would like assistance from a USPTO Customer Service Representative or access to the automated information system, call 800-786-9199 (IN USA OR CANADA) or 571-272-1000.

DJG

Andy Hughl Rimany Examine